S72	76	(nano\$1probe (nano adj probe)) same (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 13:06
S73	99	S72 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	Z O	2005/03/23 15:23
S74	7	S73 and ((project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment))	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR .	NO	2005/08/08 13:16
S75	E	S74 and (conduct\$5 near2 (wir\$3 cord\$3 cabl\$3 line link channel connect\$5 lead\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	Z <sub>O</sub>	2005/03/23 15:27
S76	_	(324/724.ccls.) and @ad<"20030922" and @pd>"20050316"	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR	Z <sub>O</sub>	2005/08/08 11:21
S77	4	(324/722,691.ccls.) and @ad<"20030922" and @pd>"20050316"	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR .	NO	2005/08/08 11:21
S78	4	(324/649,600.ccls.) and @ad<"20030922" and @pd>"20050316"	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 11:21
S79	82	(324/751,752,754,755,757,758.ccls.) and @ad<"20030922" and @pd>"20050316"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 11:22

Search History 8/17/05 4:03:23 PM Page 10 C:UDocuments and Settings\text{HNguyen26\text{My} Documents\text{EAST\text{Workspaces\10667049.wsp}}

162 (324/72.5,715,765,158.1.ccls.) and @ad			<"20030922" and @pd>"20050316"	US-PGPUB; USPAT; EPO; JPO;	OR	N O	2005/08/08 11:22
				DERWENT ; IBM_TDB			
3 (324/437,445-447.ccls.) and @ad<"20030922" and @pd>"20050316"		122" and	d @pd>"20050316"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO O	2005/08/08 11:22
1 (324/690,696.ccls.) and @ad<"20030922" and @pd>"20050316"		and @pc	od>"20050316"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 11:53
(nano\$1probe (nano adj probe)) same (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane) and @ad<"20030922"		ostrate ma	aterial \$5film coat\$3 layer sheet pad 22"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 13:39
7 S83 and ((project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment compartment component assembly unit tool))		ar2 (po sembly	ortion part member moiety parcel piece y unit tool))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 13:39
168 (nano\$1probe (nano adj probe)) and @ad<"20030922"	<del></del>	"200309		US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO O	2005/08/08 14:42
S85 and ((project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment compartment component assembly unit tool))		near2 (po assembly	ortion part member moiety parcel piece y unit tool))	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 13:40
1462 (600/11,459,462.ccls.) and @ad<"20030922"		22"		US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO	2005/08/08 14:25

Search History 8/17/05 4:03:23 PM Page 11 C:\Documents and Settings\H\Nguyen26\My Documents\EAST\Workspaces\10667049.wsp

2005/08/10 09:16	2005/08/08 14:35	2005/08/08 14:42	2005/08/08 15:02	2005/08/08 15:07	2005/08/10 09:25	2005/08/10 09:17
NO	OFF	NO	NO .	NO	N O	NO
OR	S S	OR	OR	OR	OR	OR
US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	USPAT; USPAT; EPO; JPO; DERWENT ; IBM_TDB	USPAT; USPAT; EPO; JPO; DERWENT ; IBM_TDB	USPAT; USPAT; EPO; IPO; DERWENT ; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB
7 (600/372,373,393.ccls.) and @ad<"20030922"	2 ("20050062488").PN.	0 S88 and (nano\$1probe (nano adj probe))	0 S89 and (nano\$1probe (nano adj probe))	((nano\$1probe (nano adj probe)) and (project\$5 protrud\$5 extend\$5) and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane) and (portion part member moiety parcel piece section segment compartment component assembly unit tool) and (plural\$5 number multipl\$5 series several set) and conduct\$5).clm.) and @ad<"20030922"	(((nano\$1probe (nano adj probe)) and (project\$5 protrud\$5 extend\$5) and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane) and (portion part member moiety parcel piece section segment compartment component assembly unit tool) and (plural\$5 number multipl\$5 series several set) and conduct\$5 and (flexible conformable adaptable adjustable bendable tractable moldable stretchable elastic extensible) and (stiff\$4 rigid\$5 \$2flexib\$5)).clm.) and @ad<"20030922"	
807						297721
688	S90	S91	S92	S93	S94	S95

96S	3762	S95 and ((project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment)) same (stiff\$4 rigid\$5 \$2flexib\$5)	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR	NO	2005/08/10 09:20
297	798	S95 and ((project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment)) near3 (stiff\$4 rigid\$5 \$2flexib\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	NO	2005/08/10 09:22
868	496	S97 and (electrode plate contact pole tip probe) with (flexib\$5 conformable adaptable adjustable bendable tractable moldable stretchable elastic extensible)	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR	NO O	2005/08/10 09:23
899	345	S97 and (electrode plate contact pole tip probe) near3 (flexib\$5 conformable adaptable adjustable bendable tractable moldable stretchable elastic extensible)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	0	2005/08/10 09:23
S100	61	S99 and (plural\$5 number multipl\$5 series several set) near3 conduct\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR .	Z O	2005/08/10 09:26
S101	2	("6788086").PN.	US-PGPUB; USPAT; EPO; IPO; DERWENT ; IBM_TDB	OR	ОFF	2005/08/17 13:33